

ZIITEK ELECTRONIC MATERIAL & TECHNOLOGY CO., LTD

TIF[™]100-50-11US Thermally Conductive Gap Filler Pads Series

electronic components.

Outgassing (TML)

Flame Rating

TIFTM100-50-11US Series thermally conductive interface materials are applied to fill the air gaps between the heating elements and the heat dissipation fins or the metal base. Their flexibility and elasticity make them suited to coat very uneven surfaces. Heat can transmit to the metal housing or dissipation plate from the heating elements or even the entire PCB, which effecitly enhances the efficiency and life-time of the heat-generating

REV02

Visual

ASTM D374

ASTM 2240

ASTM D297

ASTM D149

ASTM D150

ASTM D257

ASTM D5470

GB-T32064

ASTM E595

UL E331100



Features

- » Good thermal conductivity: 5.0 W/mK
- » Naturally tacky needing no further adhesive coating
- » Soft and Compressible for low stress applications
- » Available in varies thickness

Application

- Cooling components to the chassis of frame
- » Set Top Box
- Car Battery & Power Supply
- » Charging Pile
- » LED TV/ Lighting
- » Graphics Card Thermal Module

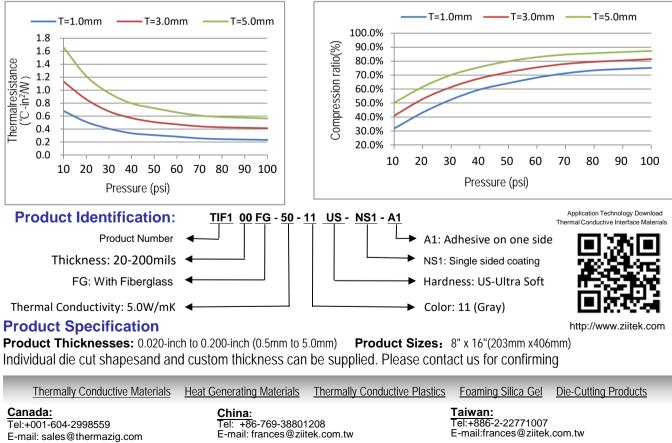
psi. vs.Thermal Resistance

Typical Properties of TIF[™]100-50-11US Series Color Gray Construction Ceramic filled silicone elastomer Thickness range 0.020"(0.5mm)~0.200" (5.0mm) Hardness 20 Shore 00 Specific Gravity 2.9 g/cc Operating Temp -40 ~160 ℃ Dielectric Breakdown Voltage >5500 VAC **Dielectric Constant@1MHz** 4.2 MHz 1.0X10¹² Ohm-cm Volume Resistivitv 5.0 W/mK Thermal Conductivity 5.0 W/mK

psi. vs. Compression Ratio

0.40%

94 -V0



The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assume legal responsibility. Users should undertake sufficient verification and testing to determine the suitability for their own particular purpose of any information or products referred to herein.